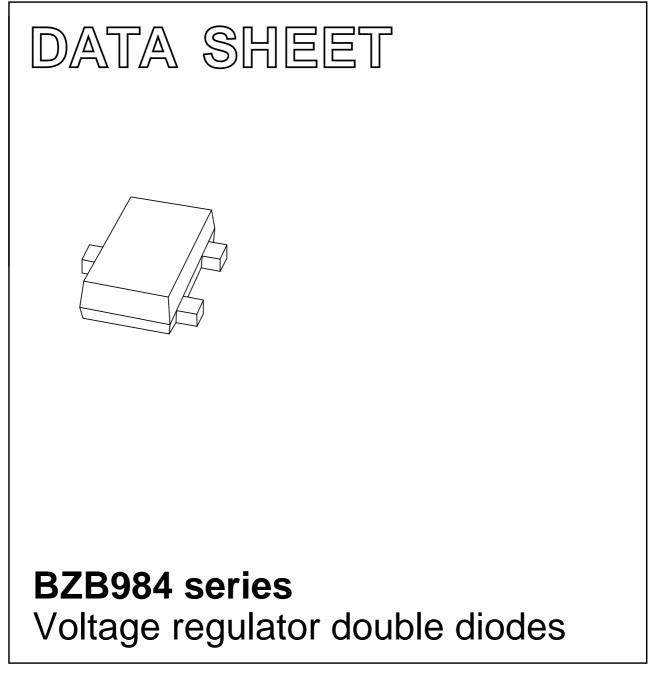
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Nov 28 2002 Jun 21



#### FEATURES

- Total power dissipation: max. 425 mW
- Approx. 5% Vz tolerance
- Ultra small flat plastic SMD package
- Working voltage range nom. 2.4 to 15 V (E24 range).

#### APPLICATIONS

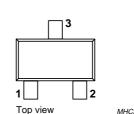
- General regulation functions
- ESD and surge protection.

#### DESCRIPTION

Low-power voltage regulator diodes in a SOT663 ultra small plastic SMD package.

#### PINNING

PIN	DESCRIPTION
1	cathode 1
2	cathode 2
3	common anode



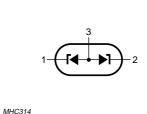


Fig.1 Simplified outline (SOT663) and symbol.

#### MARKING

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
BZB984-C2V4	91	BZB984-C3V9	96	BZB984-C6V2	9B	BZB984-C10	9G
BZB984-C2V7	92	BZB984-C4V3	97	BZB984-C6V8	9C	BZB984-C11	9H
BZB984-C3V0	93	BZB984-C4V7	98	BZB984-C7V5	9D	BZB984-C12	9J
BZB984-C3V3	94	BZB984-C5V1	99	BZB984-C8V2	9E	BZB984-C13	9K
BZB984-C3V6	95	BZB984-C5V6	9A	BZB984-C9V1	9F	BZB984-C15	9L

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>ZSM</sub>	non-repetitive peak reverse current	$t_p = 100 \ \mu s$ ; square wave; $T_{amb} = 25 \ ^{\circ}C$ ; prior to surge	see Table	e 1	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C; 2 diodes loaded; note 1	_	425	mW
		T <sub>amb</sub> = 25 °C; 1 diode loaded; note 1	-	265	mW
P <sub>ZSM</sub>	non-repetitive peak reverse dissipation	$t_p$ = 100 µs; square wave; $T_{amb}$ = 25 °C; prior to surge	_	40	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

#### Note

1. Device mounted on an FR4 printed-circuit board.

### BZB984 series

### BZB984 series

### ELECTRICAL CHARACTERISTICS

#### Total BZB984-C series

 $T_{amb}$  = 25  $^\circ C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 10 mA; see Fig.2	0.9	V
I <sub>R</sub>	reverse current			
	BZB984-C2V4	$V_R = 1 V$	50	μA
	BZB984-C2V7	$V_R = 1 V$	20	μA
	BZB984-C3V0	$V_R = 1 V$	10	μA
	BZB984-C3V3	$V_R = 1 V$	5	μA
	BZB984-C3V6	$V_R = 1 V$	5	μA
	BZB984-C3V9	$V_R = 1 V$	3	μA
	BZB984-C4V3	$V_R = 1 V$	3	μA
	BZB984-C4V7	V <sub>R</sub> = 2 V	3	μA
	BZB984-C5V1	$V_R = 2 V$	2	μA
	BZB984-C5V6	$V_R = 2 V$	1	μA
	BZB984-C6V2	$V_{R} = 4 V$	3	μA
	BZB984-C6V8	$V_R = 4 V$	2	μA
	BZB984-C7V5	$V_{R} = 5 V$	1	μA
	BZB984-C8V2	$V_R = 5 V$	700	nA
	BZB984-C9V1	V <sub>R</sub> = 6 V	500	nA
	BZB984-C10	V <sub>R</sub> = 7 V	200	nA
	BZB984-C11	V <sub>R</sub> = 8 V	100	nA
	BZB984-C12	V <sub>R</sub> = 8 V	100	nA
	BZB984-C13	V <sub>R</sub> = 8 V	100	nA
	BZB984-C15	V <sub>R</sub> = 10.5 V	50	nA

<b>Table 1</b> F T <sub>j</sub> = 25 °C 1	Per type BZE unless other	Table 1Per type BZB984-C2V4 to C15 $T_j = 25 ^{\circ}C$ unless otherwise specified.	o <b>C15</b> <u>3</u> d.						
BZB984-	WORKINC V <sub>Z</sub> at I <sub>Z</sub> =	WORKING VOLTAGE $V_{Z}$ (V) at $I_{Z} = 5 mA$	DIFI	iFFERENTIAL RESISTANCE r <sub>dif</sub> (Ω)	TIAL RESISTA r <sub>dif</sub> (Ω)	NCE	TEMP. COEFF. $S_{Z}$ (mV/K) at $I_{Ztest} = 5 mA$	DIODE CAP. C <sub>d</sub> (pF) at f = 1 MHz;	NON-REPETITIVE PEAK REVERSE CURRENT $I_{ZSM}$ (A) at $t_p = 100 \ \mu s$ ;
CXXX	Tol.	Tol. ≈5%	at I <sub>z</sub> =	= 1 mA	at $I_z = 0$	= 5 mA	(see Figs 3 and 4)	$V_{\rm R} = 0 V$	T <sub>amb</sub> = 25 °C
	MIN.	MAX.	TYP.	MAX.	TYP.	MAX.	TYP.	MAX.	MAX.
2V4	2.2	2.6	275	600	70	100	-1.3	450	6.0
2V7	2.5	2.9	300	600	75	100	-1.4	450	6.0
3V0	2.8	3.2	325	600	80	95	-1.6	450	6.0
3V3	3.1	3.5	350	600	85	95	-1.8	450	6.0
3V6	3.4	3.8	375	600	85	06	-1.9	450	6.0
3V9	3.7	4.1	400	600	85	06	-1.9	450	6.0
4V3	4.0	4.6	410	600	80	06	-1.7	450	6.0
4V7	4.4	5.0	425	500	50	80	-1.2	300	6.0
5V1	4.8	5.4	400	480	40	60	-0.5	300	6.0
5V6	5.2	6.0	80	400	15	40	1.0	300	6.0
6V2	5.8	6.6	40	150	6	10	2.2	200	6.0
6V8	6.4	7.2	30	80	6	15	3.0	200	6.0
7V5	7.0	7.9	30	80	6	15	3.6	150	4.0
8V2	7.7	8.7	40	80	6	15	4.3	150	4.0
9V1	8.5	9.6	40	100	6	15	5.2	150	3.0
10	9.4	10.6	50	150	8	20	6.0	06	3.0
11	10.4	11.6	50	150	10	20	6.9	90	2.5
12	11.4	12.7	50	150	10	25	7.9	85	2.5
13	12.4	14.1	50	170	10	30	8.8	80	2.5
15	13.8	15.6	50	200	10	30	10.7	75	2.0

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# BZB984 series

### **BZB984** series

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-s</sub>	thermal resistance from junction to soldering point	2 diodes loaded; note 1	125	K/W
		1 diode loaded; note 1	230	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	2 diodes loaded; note 2	294	K/W
		1 diode loaded; note 2	472	K/W

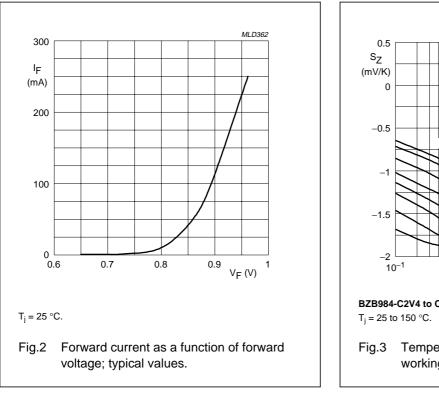
#### Notes

- 1. Solder points on cathode tabs.
- 2. Device mounted on an FR4 printed-circuit board.

#### Soldering

The only recommended soldering method is reflow soldering.

#### **GRAPHICAL DATA**



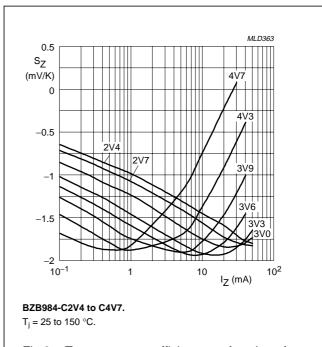
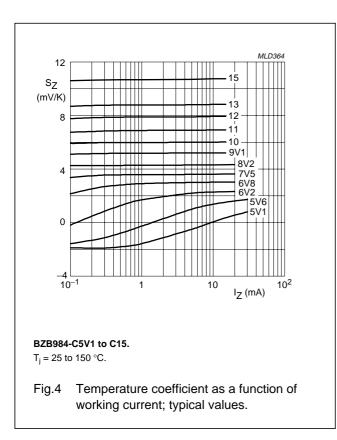


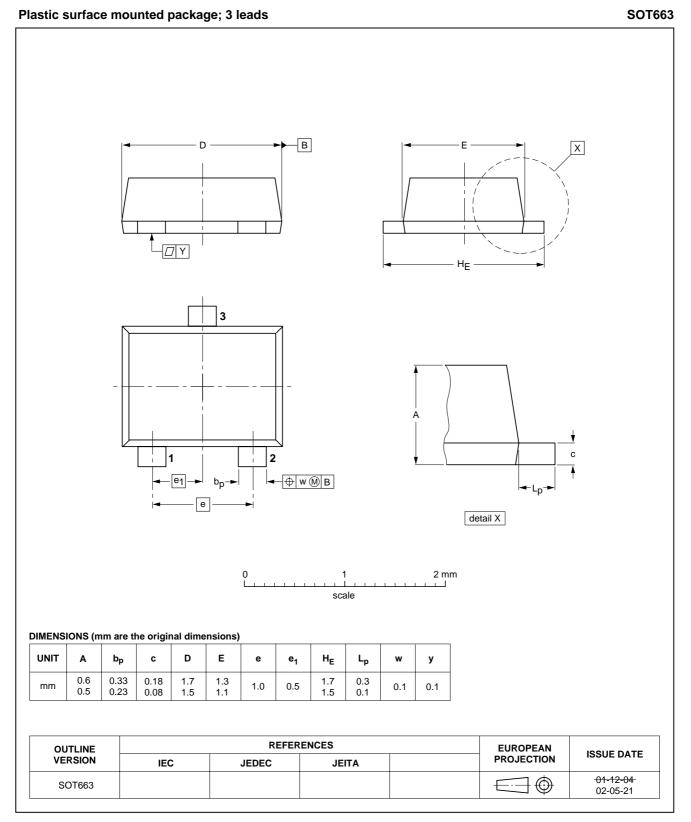
Fig.3 Temperature coefficient as a function of working current; typical values.

### **BZB984** series



### BZB984 series

#### PACKAGE OUTLINE



**BZB984** series

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DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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